

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In Re  
Appln. of: **Uwe SCHWARZ**

Group Art Unit: **2812**

Serial  
No.: **10/537,211**

Conf. No.: **1865**

Filed: **March 20, 2006**

Examiner: **Reema PATEL**

For: **PRODUCTION OF  
MICROELECTROMECHANICAL  
SYSTEMS (MEMS) USING THE  
HIGH-TEMPERATURE SILICON  
FUSION BONDING OF WAFERS**

Atty Docket  
No.: **D4695-00135**

**SUPPLEMENTAL INFORMATION DISCLOSURE STATEMENT**

Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

Sirs:

Applicant submits this Supplemental Information Disclosure Statement pursuant to 37 C.F.R. §1.56. U.S. Patent No. 6,012,336 was first cited in a parallel European application. The required fee of \$180.00 charged to Deposit Account 04-1679 (Atty Docket No. D4695-00135) is submitted herewith via EFS charge authorization.

Respectfully submitted,

Dated: July 3, 2006

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